



Material Content Data Sheet



Sales Product Name		XDPL8105		Issued		24. January 2018		
MA#		MA001641288						
Package		PG-DSO-8-58		Weight*		81.58 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.789	2.19	2.19	21931	21931
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.035	0.04		432	
	non noble metal	iron	7439-89-6	0.705	0.86		8641	
wire	non noble metal	copper	7440-50-8	28.624	35.09	36.00	350851	360032
	noble metal	palladium	7440-05-3	0.000	0.00		6	
	non noble metal	copper	7440-50-8	0.046	0.06	0.06	558	564
encapsulation	organic material	carbon black	1333-86-4	0.146	0.18		1793	
	plastics	epoxy resin	-	4.731	5.80		57987	
	inorganic material	silicondioxide	60676-86-0	43.894	53.81	59.79	538027	597807
leadfinish	non noble metal	tin	7440-31-5	0.814	1.00	1.00	9975	9975
plating	noble metal	silver	7440-22-4	0.084	0.10	0.10	1034	1034
glue	plastics	acrylic resin	-	0.141	0.17		1731	
	noble metal	silver	7440-22-4	0.565	0.69	0.86	6926	8657
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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